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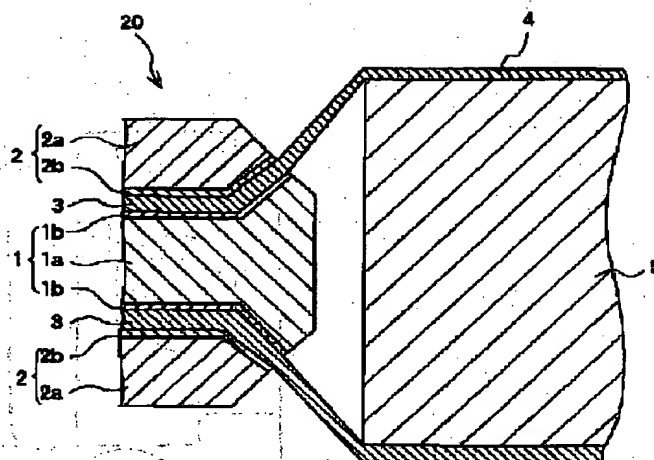
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TITLE : DIE FOR RESIN EXPANDED SHEET
MANUFACTURING DEVICE, AND
MANUFACTURE OF RESIN
EXPANDED SHEET USING THE DIE



ABSTRACT : PROBLEM TO BE SOLVED: To provide a die used for a resin expanded sheet manufacturing device, by which there is no coarseness on the surface of an obtained resin expanded sheet, and also, there is no adhesion of burr, and a resin expanded sheet having an excellent appearance can be manufactured, and which is advantageous in durability and cost, and also, can be used for various kinds of resins, and a manufacturing method of a resin expanded sheet using this die.

SOLUTION: This die 20 comprises a core 1 comprising a core main body 1a and a core coating layer 1b on which a coating is applied with titanium nitride or tungsten carbide, and an out ring 21 comprising an out ring main body 2a and an out ring coating layer 2b on which a coating with titanium nitride or tungsten carbide, or a nitriding is applied.

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